


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	AMS/18/11228	
1.3 Title of PCI	Notification of Metal Mask Change on VP11.	
1.4 Product Category	See Product List	
1.5 Issue date	2018-12-12	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Domenico ARRIGO
2.1.2 Marketing Manager	Fulvio PULICELLI
2.1.3 Quality Manager	Alessandro PLATINI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Process)	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	Catania fab (Italy) as Diffusion plant; Calamba (Philippines) as Assembly Plant; Agrate (Italy) and Calamba (Philippines) as Test & Finishing plant.

4. Description of change

	Old	New
4.1 Description	WAFER Genealogy: VP11AC5 AGRATE (Italy) as T&F Plant.	WAFER Genealogy: VP11AD5 AGRATE (Italy) and CALAMBA (Philippines) as T&F Plant.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	The implementation of the change improves the yield and increases the capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	New FG
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7. Timing / schedule

7.1 Date of qualification results	2018-11-21
7.2 Intended start of delivery	2019-01-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

11228 Public product.pdf



10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ISO8200BQ	

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